




## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752 Distribute</b>	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	<b>Material Info Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>
<b>* : Required Field</b>			

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2017-06-07</b>
<b>Company Unique ID</b>	<b>NL 008751171B01</b>		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>Laurent Tosi</b>	<b>Representative Title</b>	<b>MMS MD CHAMPION</b>
<b>Representative Phone *</b>	<b>(+33) 442 685 795</b>	<b>Representative Email *</b>	<b>laurent.tosi@st.com</b>
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

Uncertainty Statement	
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Legal Statement	
<b>Supplier Acceptance *</b>	<b>true</b>
<b>Legal Declaration *</b>	<b>Standard</b>
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
M24C32-FMC6TG	CGZW*24321TA	A	P1C7	2017-06-07
	Amount	UoM	Unit type	ST ECOPACK Grade
	16.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	2X3X0.6	8	No lead	
Comment	UFD FPN 2x3x0.6			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	Plating underlayer	755

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	CGZW*24321TA				5999999.0	1000003.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	0.233	mg	supplier	die	Silicon (Si)	7440-21-3		0.221	mg	948498	13813
				supplier	metallization	Aluminium (Al)	7429-90-5		0.001	mg	4292	63
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	4292	63
				supplier	Passivation	Silicon Oxide	7631-86-9		0.010	mg	42918	625
Lead-frame	M-011 Other inorganic materials	3.007	mg	supplier	alloy	Copper (Cu)	7440-50-8		2.918	mg	970270	182353
				supplier	alloy	Iron (Fe)	7439-89-6		0.070	mg	23358	4390
				supplier	alloy	Zinc (Zn)	7440-66-6		0.004	mg	1195	225
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.003	mg	836	157
				supplier	coating	Nickel (Ni)	7440-02-0		0.012	mg	3980	748
				supplier	coating	Palladium (Pd)	7440-05-3		0.001	mg	255	48
				supplier	coating	Gold (Au)	7440-57-5		0.000	mg	106	20
Die Attach	M-011 Other inorganic materials	0.335	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		0.229	mg	684000	14341
				supplier	glue or soft solder	methylene diacrylate	42594-17-2		0.084	mg	250000	5242
				supplier	glue or soft solder	Dicyclopentenyloxyethyl methacrylate	68586-19-6		0.010	mg	30000	629
				supplier	glue or soft solder	Polymer of Polybutadiene + Anhydride	Proprietary		0.010	mg	30000	629
				supplier	glue or soft solder	Palladium (Pd)	7440-05-3		0.000	mg	1000	21
Wires	M-011 Other inorganic materials	0.011	mg	supplier	glue or soft solder	Bis(α,α-dimethylbenzyl) peroxide	80-43-3		0.002	mg	5000	105
				supplier	Bonding wire	Copper (Cu)	7440-50-8		0.011	mg	1000000	664
Encapsulation	M-011 Other inorganic materials	12.414	mg	supplier	Moulding Compound	silica vitreous	60676-86-0		10.908	mg	878734	681775
				supplier	Moulding Compound	Phenolic resin	Proprietary		0.572	mg	46101	35768
				supplier	Moulding Compound	Biphenyl epoxy resin	85954-11-6		0.448	mg	36079	27992
				supplier	Moulding Compound	carbon black	1333-86-4		0.025	mg	2004	1555
				supplier	Moulding Compound	Zinc hydroxide	20427-58-1		0.012	mg	1002	778
Finishing	M-011 Other inorganic materials	0.000	mg	supplier	Moulding Compound	Biphenyl epoxy resin	85954-11-6		0.448	mg	36079	27992
				supplier	connections coating	Nickel (Ni)	7440-02-0		0.000	mg	916800	7
				supplier	connections coating	Palladium (Pd)	7440-05-3		0.000	mg	58700	0
				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	24500	0